

## **ABSTRACT OF THE DISCLOSURE**

The present invention relates to a polishing apparatus for polishing a workpiece ~~to be polished~~, such as a semiconductor wafer, to a flat mirror finish. The polishing apparatus comprises a polishing table having a polishing surface, and a top ring, and the workpiece ~~to be polished~~ is interposed between the polishing table and the top ring and pressed at a predetermined pressure to polish the workpiece. The polishing apparatus comprises at least two dressing units for dressing the polishing surface by being brought into contact with ~~a~~ the polishing surface, which is a surface of a polishing cloth.